

Title (en)

OBJECT PROCESSING METHOD AND DEVICE

Title (de)

OBJEKTVERARBEITUNGSVERFAHREN UND -VORRICHTUNG

Title (fr)

PROCÉDÉ ET DISPOSITIF DE TRAITEMENT D'OBJET

Publication

EP 3766993 A4 20211208 (EN)

Application

EP 19766700 A 20190228

Priority

- JP 2018049818 A 20180316
- JP 2019007819 W 20190228

Abstract (en)

[origin: EP3766993A1] An object-processing method applies a specific process to an object to be processed (X) by connecting a power source (4) to the object to be processed.

IPC 8 full level

C21D 9/00 (2006.01); **B21J 1/06** (2006.01); **B21K 1/36** (2006.01); **B21K 29/00** (2006.01); **C21D 1/84** (2006.01); **C21D 9/40** (2006.01); **C21D 11/00** (2006.01); **F25B 21/00** (2006.01); **F25B 23/00** (2006.01)

CPC (source: EP US)

B21J 1/06 (2013.01 - EP US); **B21K 1/36** (2013.01 - EP); **B21K 29/00** (2013.01 - EP); **C21D 1/84** (2013.01 - EP); **C21D 9/00** (2013.01 - EP); **C21D 9/40** (2013.01 - EP); **C21D 11/005** (2013.01 - EP); **F25B 21/00** (2013.01 - US); **C21D 9/0068** (2013.01 - US); **C21D 11/005** (2013.01 - US)

Citation (search report)

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- [X] EP 2960599 A1 20151230 - LOCKHEED CORP [US]
- [XA] JP H11106830 A 19990420 - SUMITOMO ELECTRIC INDUSTRIES
- [XA] JP S5827921 A 19830218 - HITACHI LTD
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- [X] US 2014345296 A1 20141127 - DEFAY EMMANUEL [FR], et al
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- See references of WO 2019176562A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)

EP 3766993 A1 20210120; **EP 3766993 A4 20211208**; CN 111819297 A 20201023; JP WO2019176562 A1 20201203; US 2021016342 A1 20210121; WO 2019176562 A1 20190919

DOCDB simple family (application)

EP 19766700 A 20190228; CN 201980019144 A 20190228; JP 2019007819 W 20190228; JP 2020505760 A 20190228; US 201916981017 A 20190228